

## PATENT ASSIGNMENT

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| SUBMISSION TYPE:   | NEW ASSIGNMENT             |
| NATURE OF CONVEYANCE:  | ASSIGNMENT                 |
| CONVEYING PARTY DATA   |                            |
| Name   | Execution Date             |
| Zvi Or-Bach  | 06/01/2012                 |
| RECEIVING PARTY DATA   |                            |
| Name:  | MonolithIC 3D Inc.         |
| Street Address:  | 3555 Woodford Drive        |
| City:  | San Jose                   |
| State/Country:   | CALIFORNIA                 |
| Postal Code:   | 95124                      |
| PROPERTY NUMBERS Total: 1  |                            |
| Property Type  | Number                     |
| Application Number:  | 12963659                   |
| CORRESPONDENCE DATA  |                            |
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| Total Attachments: 1<br>source=M3D-013_Assignment_Br3_s#page1.tif                    |                            |

OP \$40.00 12963659

**ASSIGNMENT**

Whereas, we, **Zvi Or-Bach, residing at 3555 Woodford Drive, San Jose, California 95124, respectively;** (hereinafter called "Assignor(s)"), have made a certain invention, and executed Patent Application entitled:

**METHOD FOR FABRICATION OF A SEMICONDUCTOR DEVICE AND STRUCTURE**

as described in Patent Application Serial No. 12/963,659 and filed on Dec, 9, 2010; and

Whereas, MonolithIC 3D Inc., a company located at 3555 Woodford Drive, San Jose, California 95124 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

**INVENTOR:**

DATE on 6.1.11

(Zvi

First Name

Middle Initial

Or-Bach)

Last Name